

EK-TM4C123GXL-BOOST-CAPSENSEFirmware Development Package

USER'S GUIDE

Copyright

Copyright © 2012-2015 Texas Instruments Incorporated. All rights reserved. Tiva and TivaWare are trademarks of Texas Instruments Instruments. ARM and Thumb are registered trademarks and Cortex is a trademark of ARM Limited. Other names and brands may be claimed as the property of others.

APlease be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this document.

Texas Instruments 108 Wild Basin, Suite 350 Austin, TX 78746 www.ti.com/tiva-c







Revision Information

This is version 2.1.2.111 of this document, last updated on December 16, 2015.

Table of Contents

| Cop | yright | 2 |
|-----|-------------------------------------|---|
| Rev | sion Information | 2 |
| 1 | Introduction | 5 |
| 2 | Example Applications | 7 |
| 2.1 | Capacitive Touch Example (capsense) | 7 |
| IMP | ORTANT NOTICE | 8 |

December 16, 2015 3

1 Introduction

The Texas Instruments® Tiva™ C Series EK-TM4C123GXL-BOOST-CAPSENSE evaluation board (Tiva C Series TM4C123G LaunchPad) is a low cost platform that can be used for software development and to prototype a hardware design. A variety of BoosterPacks are available to quickly extend the LaunchPad's features.

This document describes the example applications that are provided for the EK-TM4C123GXL when paired with the 430BOOST-SENSE1 BoosterPack commonly known as the Capacitive Touch BoosterPack. The TM4C123GH6PM Tiva C Series micro-controller does not have the capacitive sense hardware assistance features like those of the certain MSP430™ devices. Therefore, these example applications assume that the user has added the optional resistors to the 430BOOST-SENSE1 BoosterPack. Resistance value of 200k ohms is recommended. See http://processors.wiki.ti.com/index.php/tm4c123g-launchpad for calibration procedure.

December 16, 2015 5

2 Example Applications

The example applications show how to use features of the Cortex-M4F microprocessor, the peripherals on the Tiva C Series microcontroller, and the drivers provided by the peripheral driver library. These applications are intended for demonstration and as a starting point for new applications.

There is an IAR workspace file (ek-tm4c123gxl-boost-capsense.eww) that contains the peripheral driver library project, USB library project, and all of the board example projects, in a single, easy to use workspace for use with Embedded Workbench version 6.

There is a Keil multi-project workspace file (ek-tm4c123gx1-boost-capsense.mpw) that contains the peripheral driver library project, USB library project, and all of the board example projects, in a single, easy to use workspace for use with uVision.

All of these examples reside in the examples/boards/ek-tm4c123gxl-boost-capsense subdirectory of the firmware development package source distribution.

2.1 Capacitive Touch Example (capsense)

An example that works with the 430BOOST-SENSE1 capactive sense BoosterPack, originally designed for the MSP430 LaunchPad.

The TM4C123GH6PM does not have the capacitive sense hardware assisted peripheral features of some MSP430 chips. Therefore it is required that the user install surface mount resistors on the pads provided on the bottom of the capacitive sense BoosterPack. Resistor values of 200k ohms are are recommended. Calibration may be required even when using 200k ohm resistors as each capsense booster pack varies. Calibration is required for resistors other than 200k ohm.

See the wiki page for calibration procedure. $\verb|http://processors.wiki.ti.com/index.php/tm4c123g-law| and the control of the$

December 16, 2015 7

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have not been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Wireless Connectivity

P Audio www.ti.com/audio **Amplifiers** amplifier.ti.com **Data Converters** dataconverter.ti.com **DLP® Products** www.dlp.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com OMAP Applications Processors www.ti.com/omap

Applications

Automotive and Transportation www.ti.com/automotive Communications and Telecom www.ti.com/communications Computers and Peripherals www.ti.com/computers Consumer Electronics www.ti.com/consumer-apps **Energy and Lighting** www.ti.com/energy Industrial www.ti.com/industrial Medical www.ti.com/medical Security www.ti.com/security Space, Avionics and Defense www.ti.com/space-avionics-defense Video and Imaging www.ti.com/video

TI E2E Community e2e.ti.com www.ti.com/wirelessconnectivity

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2012-2015, Texas Instruments Incorporated